

### MiniSKiiP<sup>®</sup> 3

### 3-phase bridge rectifier

#### SKiiP 39AN16V1

#### Features\*

- NEW SKR PEP diode-technology for enhanced power and environmental robustness
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

- Max. case temperature limited to  $T_{C}{=}125^{\circ}C$
- Product reliability results valid for T<sub>j</sub>≤150°C (recommended T<sub>i on</sub>=-40...+150°C)
- T<sub>j,op</sub>=-40...+150°C)
  MiniSKiiP "Technical Explanations" and "Mounting Instructions" are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document: "Technical Explanations Thermal Interface Materials"

Absolute	Absolute Maximum Ratings								
Symbol	Conditions		Values	Unit					
Diode 1									
V <sub>RRM</sub>	T <sub>j</sub> = 25 °C		1600	V					
	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 25 °C	365	Α					
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	277	Α					
l <sub>F</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 25 °C	467	1600      V        365      A        277      A        467      A        358      A        2300      A					
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 70 °C	358	Α					
I <sub>FSM</sub>	10 ms, sin 180°, T <sub>j</sub>	= 150 °C	2300	А					
i <sup>2</sup> t	10 ms, sin 180°, T <sub>j</sub>	= 150 °C	26450	A²s					
Tj			-40 175	°C					

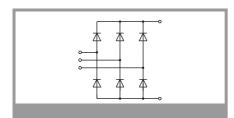
#### Absolute Maximum Ratings

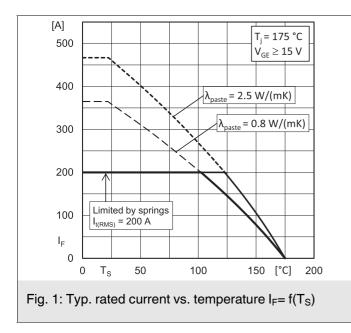
Symbol	Conditions	Values	Unit
Module			
I <sub>t(RMS)</sub>	20 A per spring	200	Α
T <sub>stg</sub>	module without TIM	-40 125	°C
V <sub>isol</sub>	AC sinus 50 Hz, t = 1 min	2500	V

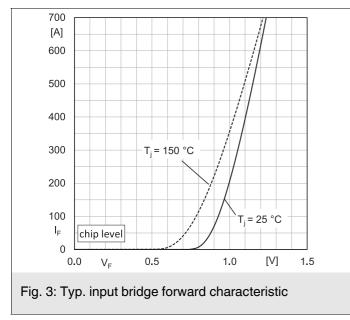
### Characteristics Symbol Conditions

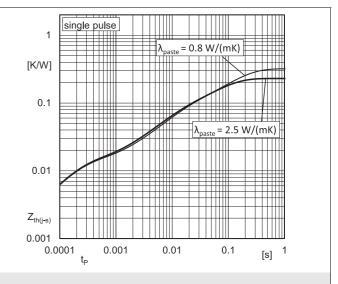
Symbol	Conditions		min.	typ.	max.	Unit
Diode 1						
V <sub>F</sub>	I <sub>F</sub> = 154 A	T <sub>j</sub> = 25 °C		0.97	1.20	V
	V <sub>GE</sub> = 0 V chiplevel	T <sub>j</sub> = 150 °C		0.84	1.07	V
V <sub>F0</sub>	chiplevel	T <sub>j</sub> = 25 °C		0.89	1.09	V
		T <sub>j</sub> = 150 °C		0.73	0.92	V
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		0.53	0.71	mΩ
		T <sub>j</sub> = 150 °C		0.74	1.00	mΩ
I <sub>R</sub>	T <sub>j</sub> = 150 °C, V <sub>R</sub>			6	mA	
R <sub>th(j-s)</sub>	per Diode, $\lambda_{pas}$		0.32		K/W	
R <sub>th(j-s)</sub>	per Diode, $\lambda_{pas}$		0.23		K/W	

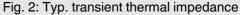
Characteristics							
Symbol	Conditions	min.	typ.	max.	Unit		
Module							
Ms	to heat sink	2		2.5	Nm		
w	weight		82		g		





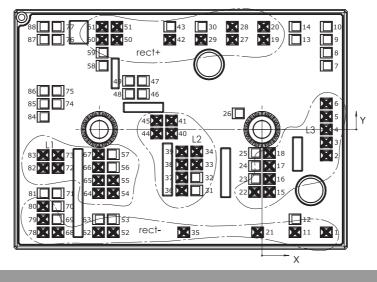




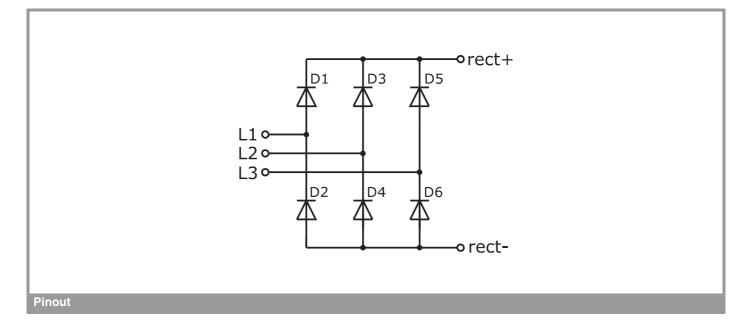


Pin out											
Pin	X	Ŷ	Function	Pin	X	Y	Function	Pin	X	Ŷ	Function
1	15,83	-25,30	rect-	31	-16,05	-15,02		61	-39,33	25,30	rect+
2	15,83	-6,40	L3	32	-16,05	-11,82		62	-40,23	-25,30	rect-
3	15,83	-3,20	L3	33	-16,05	-8,62	L2	63	-40,23	-22,10	
4	15,83	0	L3	34	-16,05	-5,42	L2	64	-40,23	-15,70	L1
5	15,83	3,20	L3	35	-19,23	-25,30	rect-	65	-40,23	-12,50	L1
6	15,83	6,40	L3	36	-19,70	-15,02	L2	66	-40,23	-9,30	L1
7	15,83	15,70		37	-19,70	-11,82	L2	67	-40,23	-6,10	L1
8	15,83	18,90		38	-19,70	-8,62	L2	68	-50,18	-25,30	rect-
9	15,83	22,10		39	-19,70	-5,42	L2	69	-50,18	-22,10	
10	15,83	25,30		40	<b>-</b> 22,26	-1,00	L2	70	-50,18	-18,90	
11	8,13	-25,30	rect-	41	-22,26	2,20	L2	71	-50,18	-15,70	
12	8,13	-22,10		42	-22,68	22,10	rect+	72	-50,18	-9,50	L1
13	8,13	22,10		43	-22,68	25,30		73	-50,18	-6,30	L1
14	8,13	25,30		44	-25,91	-1,00	L2	74	-50,18	6,30	
15	1,83	-15,39	L3	45	-25,91	2,20	L2	75	-50,18	9,50	
16	1,83	-12,19	L3	46	-29,18	8,74		76	-50,18	22,10	
17	1,83	-8,99	L3	47	-29,18	11,94		77	-50,18	25,30	
18	1,83	-5,79	L3	48	-32,83	8,74		78	-53,83	-25,30	rect-
19	0,43	22,10	rect+	49	-32,83	11,94		79	-53,83	-22,10	rect-
20	0,43	25,30	rect+	50	-35,68	22,10	rect+	80	-53,83	-18,90	rect-
21	-1,08	-25,30	rect-	51	-35,68	25,30	rect+	81	-53,83	-15,70	
22	-1,83	-15,39	L3	52	-36,58	-25,30	rect-	82	-53,83	-9,50	L1
23	-1,83	-12,19		53	-36,58	-22,10		83	-53,83	-6,30	L1
24	-1,83	-8,99		54	-36,58	-15,70	L1	84	-53,83	3,10	
25	-1,83	-5,79		55	-36,58	-12,50	L1	85	-53,83	6,30	
26	-5,83	3,95		56	-36,58	-9,30		86	-53,83	9,50	
27	-7,28	22,10	rect+	57	-36,58	-6,10		87	-53,83	22,10	
28	-7,28	25,30	rect+	58	-39,33	15,70		88	-53,83	25,30	
29	-14,98	22,10	rect+	59	-39,33	18,90					
30	-14,98	25,30		60	-39,33	22,10	rect+				

all values in mm



**Pinout and Dimensions** 



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### **\*IMPORTANT INFORMATION AND WARNINGS**

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